

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An IC card comprising:
a substrate having a contact hole;
a display device equipped on one side of the substrate; and
a thin film integrated circuit equipped on the other side of the substrate,
wherein the display device is electrically connected to the thin film integrated
circuit through the contact hole, and
~~a display device and a thin film integrated circuit,~~
wherein:
~~driving of the display device is controlled by the thin film integrated circuit; and~~
~~a semiconductor element used for the thin film integrated circuit and the display~~
~~device is formed by using a polycrystalline semiconductor film.~~
wherein each of the display device and the thin film integrated circuit comprises a
polycrystalline semiconductor film.
2. (Original) An IC card according to claim 1, wherein the display device is a liquid crystal display device or a light emitting device.
3. (Canceled)
4. (Currently Amended) An IC card comprising:
a substrate having a contact hole;
a display device equipped on one side of the substrate; and
a thin film integrated circuit equipped on the other side of the substrate,

wherein the display device is electrically connected to the thin film integrated circuit through the contact hole,

~~a display device and a thin film integrated circuit,~~

~~wherein:~~

~~driving of the display device is controlled by the thin film integrated circuit;~~

~~a semiconductor element used for the thin film integrated circuit and the display device is formed by using a polycrystalline semiconductor film; and~~

wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film, and

wherein the IC card has a thickness of from 0.05 mm to 1 mm.

5. (Original) An IC card according to claim 4, wherein the display device is a liquid crystal display device or a light emitting device.

6. (Canceled)

7. (Currently Amended) An IC card comprising:

a substrate having a contact hole;

a display device equipped on one side of the substrate; and

a thin film integrated circuit equipped on the other side of the substrate,

wherein the display device is electrically connected to the thin film integrated circuit through the contact hole,

~~a display device and a thin film integrated circuit,~~

~~wherein:~~

~~driving of the display device is controlled by the thin film integrated circuit;~~

~~a semiconductor element used for the thin film integrated circuit and the display device is formed by using a polycrystalline semiconductor film;~~

wherein each of the display device and the thin film integrated circuit comprises a polycrystalline semiconductor film, and

wherein the display device is a passive matrix type or an active matrix type[[:]],
and

~~the display device and the thin film integrated circuit are equipped for the same printed wiring board; and~~

wherein the IC card has a thickness of from 0.05 mm to 1 mm.

8. (Original) An IC card according to claim 7, wherein the display device is a liquid crystal display device or a light emitting device.

9. (Canceled)

10. (Currently Amended) An IC card comprising:

a substrate having a contact hole;

a display device equipped on one side of the substrate; and

a plurality of thin film integrated circuits equipped on the other side of the substrate,

wherein the display device is electrically connected to the plurality of thin film integrated circuits through the contact hole,

~~a display device and a plurality of thin film integrated circuits,~~

~~wherein:~~

~~driving of the display device is controlled by the plurality of thin film integrated circuits;~~

~~a semiconductor element used for the plurality of thin film integrated circuits and the display device is formed by using a polycrystalline semiconductor film;~~

wherein each of the display device and the plurality of thin film integrated circuits comprises a polycrystalline semiconductor film,

wherein the plurality of thin film integrated circuits are laminated[[:]], and
~~the display device and the plurality of thin film integrated circuits are equipped for~~
~~the same printed wiring board; and~~
wherein the IC card has a thickness of from 0.05 mm to 1 mm.

11. (Original) An IC card according to claim 10, wherein thicknesses of the plurality of thin film integrated circuits are each from 1 μm to 5 μm .

12. (Original) An IC card according to claim 10, wherein the display device is a liquid crystal display device or a light emitting device.

13. (Canceled)

14. (New) An IC card according to claim 1, wherein the substrate is a printed wiring board.

15. (New) An IC card according to claim 14, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

16. (New) An IC card according to claim 1, wherein the display device is equipped on one side of the substrate by an adhesive agent.

17. (New) An IC card according to claim 1, further comprising a plurality of antenna coils.

18. (New) An IC card according to claim 4, wherein the substrate is a printed wiring board.

19. (New) An IC card according to claim 18, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

20. (New) An IC card according to claim 4, wherein the display device is equipped on one side of the substrate by an adhesive agent.

21. (New) An IC card according to claim 4, further comprising a plurality of antenna coils.

22. (New) An IC card according to claim 7, wherein the substrate is a printed wiring board.

23. (New) An IC card according to claim 22, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

24. (New) An IC card according to claim 7, wherein the display device is equipped on one side of the substrate by an adhesive agent.

25. (New) An IC card according to claim 7, further comprising a plurality of antenna coils.

26. (New) An IC card according to claim 10, wherein the substrate is a printed wiring board.

27. (New) An IC card according to claim 26, wherein the printed wiring board is selected from the group consisting of a ceramic substrate, a glass epoxy substrate and a polyimide substrate.

28. (New) An IC card according to claim 10, wherein the display device is equipped on one side of the substrate by an adhesive agent.

29. (New) An IC card according to claim 10, further comprising a plurality of antenna coils.